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## Declaration of Compliance RoHS & RoHS 2 No Exemptions

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Dear Valued Customers,

January 6, 2021

Semtech Corporation hereby declares products listed below to be compliant with the requirements for restricted substances listed in European Parliament's **RoHS Directive 2011/65/EU** issued June 8, 2011, commonly referred to as "RoHS2". The following table lists the restricted materials and their respective allowable limits:

Semtech part numbers: SC4501MSETRT

| RoHS Restricted Substance             | Allowable Limit         |
|---------------------------------------|-------------------------|
| Cadmium and its compounds*            | 100 ppm (0.01 weight %) |
| Mercury and its compounds             | 1000 ppm (0.1 weight %) |
| Hexavalent chromium and its compounds | 1000 ppm (0.1 weight %) |
| Lead and its compounds                | 1000 ppm (0.1 weight %) |
| Polybrominated biphenyls (PBB)        | 1000 ppm (0.1 weight %) |
| Polybrominated diphenyl ethers (PBDE) | 1000 ppm (0.1 weight %) |

We further declare that products do not contain the "RoHS2" chemical substances listed below pursuant to EU directive 2015/863 amendment to Annex II of EU RoHS 2 (2011/65/EU):

| RoHS2 Restricted Substance          | Allowable Limit |
|-------------------------------------|-----------------|
| Diisobutyl phthalate (DIBP)         | <1000 ppm       |
| Bis (2-ethylhexyl) phthalate (DEHP) | <1000 ppm       |
| Butyl benzyl phthalate (BBP)        | <1000 ppm       |
| Dibutyl phthalate (DBP)             | <1000 ppm       |

As part of Semtech Corporation's environmental compliance program, the following substance which is used as a flame retardant is not intentionally added to our product or processes of manufacture.

| Restricted Substance           | Allowable Limit |
|--------------------------------|-----------------|
| Hexabromocyclododecane (HBCDD) | <1000 ppm       |



For Semtech products that exceed the allowable limits per homogeneous material level, we have identified the exception(s) below;

- ☒ No exemption taken.
- ☐ 1. Mercury in compact fluorescent lamps not exceeding 5 mg per lamp.
- ☐ 2a. Mercury in straight fluorescent lamps for general purposes not exceeding 10 mg in halophosphate lamps.
- ☐ 2b. Mercury in straight fluorescent lamps for general purposes not exceeding 5 mg in triphosphate lamps with a normal life.
- ☐ 2c. Mercury in straight fluorescent lamps for general purposes not exceeding 8 mg in triphosphate lamps with long lifetime.
- ☐ 3. Mercury in straight fluorescent lamps for special purposes.
- ☐ 4. Mercury in other lamps not specifically mentioned in this list.
- ☐ 5. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- ☐ 6a. Lead as an alloying element in steel containing up to 0.35% lead by weight.
- ☐ 6b. Lead as an alloying element in aluminum containing up to 0.4% lead by weight.
- ☐ 6c. Lead as an alloying element in copper containing up to 4% lead by weight.
- ☐ 7a. Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).
- ☐ 7b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- ☐ 7c. Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- ☐ 8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC amending Directive 76/769/EEC relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- ☐ 9. Hexavalent chromium as an anti-corrosion of the carbon steel cooling system in absorption refrigerators.
- ☐ 10a. Deca BDE in polymeric applications.
- ☐ 10b. Lead in lead-bronze bearing shells.
- ☐ 11. Lead used in compliant pin connector systems.
- ☐ 12. Lead as a coating material for a thermal conduction module c-ring.
- ☐ 13a. Lead in optical and filter glass.



- ☐ 13b. Cadmium in optical and filter glass.
- ☐ 14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- ☐ 15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.

#### **CE Marking**

RoHS 2 Directive also requires CE marking on products which are defined within a listing of 20 product group categories. This listing can be reviewed at, <http://www.ce-marking.org/what-product.html>. The Semtech product you are interested in and identified within this declaration, do not fall within those categories and therefore, do not require CE marking.

#### **RoHS Compliance Table; Product Information**

Semtech Corporation invites the customer to visit our website, [www.semtech.com](http://www.semtech.com) and review our RoHS compliance information with signed Hazardous Substance Declaration of Non-Use.

Semtech Corporation is pleased for the opportunity to address your needs and look forward to a continued and successful business relationship. Please refer to your Semtech sales representative for product orders, sales and quotes.

If you have any questions, do not hesitate to give me a call.

Sincerely,

A handwritten signature in blue ink that reads 'Randy Biddle' with a stylized underline.

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